TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSVI)

# 2SK3568

## **Switching Regulator Applications**

• Low drain-source ON resistance: RDS (ON) =  $0.4 \Omega$  (typ.)

• High forward transfer admittance:  $|Y_{fs}| = 8.5S$  (typ.)

• Low leakage current: IDSS = 100  $\,\mu$  A (VDS = 500 V)

• Enhancement mode:  $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

### Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	500	V	
Drain-gate voltage (F	$R_{GS} = 20 \text{ k}\Omega$ )	$V_{DGR}$	500	٧	
Gate-source voltage		$V_{GSS}$	±30	V	
Drain current	DC (Note 1)	ID	12	А	
	Pulse (t = 1 ms) (Note 1)	I <sub>DP</sub>	48		
Drain power dissipati	on (Tc = 25°C)	P <sub>D</sub>	40	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	364	mJ	
Avalanche current		I <sub>AR</sub>	12	Α	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	4	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

# Unit: mm \$\delta 3.2 \pm 0.2 \quad \text{10 \pm 0.3} \quad \text{2.7 \pm 0.2} \quad \text{2.54} \quad \text{2.54} \quad \quad \text{2.54} \quad \quad \text{2.54} \quad \quad \quad \text{2.7 \pm 0.2} \quad \qua

Weight: 1.7 g (typ.)

### **Thermal Characteristics**

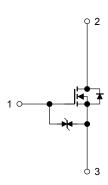
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	3.125	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V<sub>DD</sub> = 90 V, T<sub>Ch</sub> = 25°C(initial), L = 4.3 mH, I<sub>AR</sub> = 12 A, R<sub>G</sub> = 25  $\Omega$ 

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.





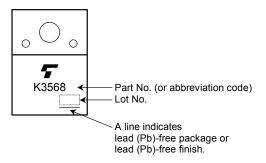
# Electrical Characteristics (Ta = 25°C)

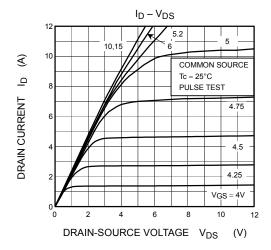
Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Gate-source brea	kdown voltage	V (BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cut-off curre	ent	I <sub>DSS</sub>	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source brea	akdown voltage	V (BR) DSS	$I_D = 10$ mA, $V_{GS} = 0$ V	500	_	_	V
Gate threshold vo	oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source ON	resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6 A	_	0.4	0.52	Ω
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 6 A	3.5	8.5	_	S
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	1500	_	pF
Reverse transfer capacitance		C <sub>rss</sub>		_	15	_	
Output capacitance		Coss		_	180	_	
Switching time	Rise time	t <sub>r</sub>	$\begin{array}{c c} 10 \text{ V} \\ \text{V}_{\text{GS}} \\ 0 \text{ V} \end{array}$ $\begin{array}{c c} \text{I}_{\text{D}} = 6 \text{ A} & \text{V}_{\text{OUT}} \\ \text{V}_{\text{DS}} \approx 200 \text{ V} \end{array}$		22		
	Turn-on time	t <sub>on</sub>			50	-	20
	Fall time	t <sub>f</sub>			36		ns
	Turn-off time	t <sub>off</sub>	Duty $\leq$ 1%, $t_W = 10 \mu s$	_	170	_	
Total gate charge		Qg		_	42	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}$	_	23	_	nC
Gate-drain charge		Q <sub>gd</sub>		_	19	_	

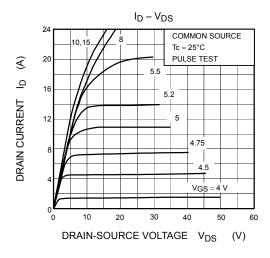
# Source-Drain Ratings and Characteristics (Ta = 25°C)

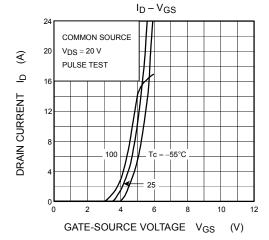
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	12	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	48	Α
Forward voltage (diode)	V <sub>DSF</sub>	$I_{DR} = 12 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	$I_{DR} = 12 \text{ A}, V_{GS} = 0 \text{ V},$	_	1200	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> /dt = 100 A/μs	_	16	_	μС

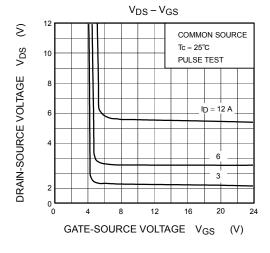
# Marking

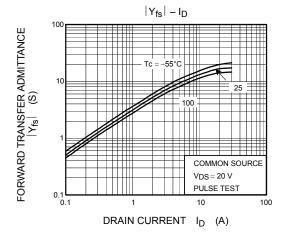


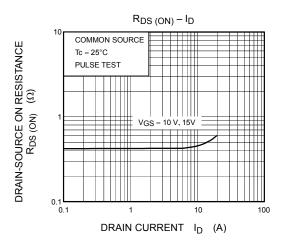


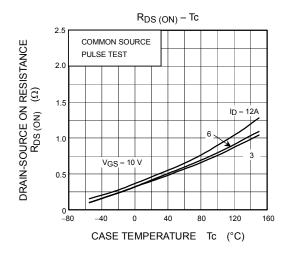


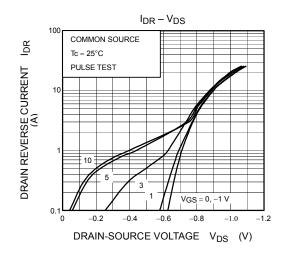


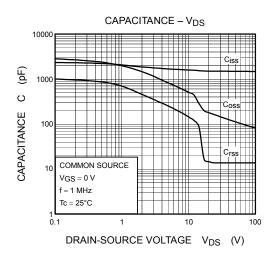


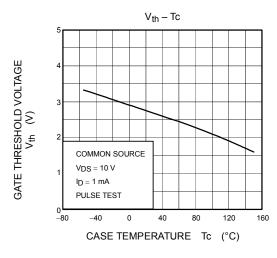


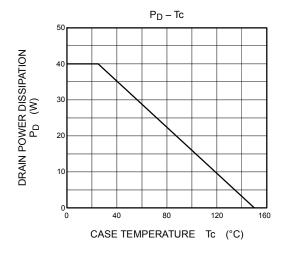


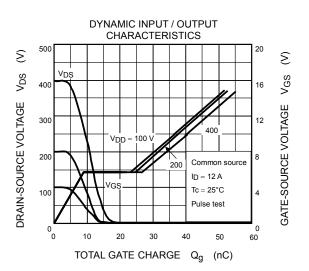


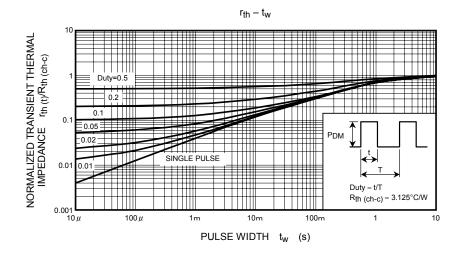


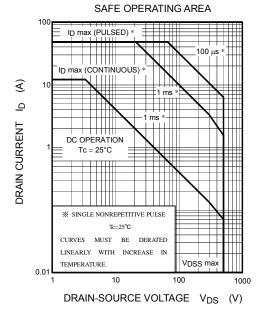


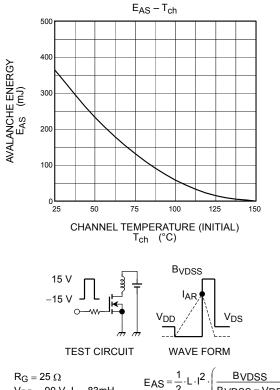












$$\mathsf{EAS} = \frac{1}{2} \cdot L \cdot l^2 \cdot \left( \frac{\mathsf{BVDSS}}{\mathsf{BVDSS} - \mathsf{VDD}} \right)$$

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Handbook" etc...

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